

Electronic Patent Application Fee Transmittal

Application Number:	10823221
Filing Date:	13-Apr-2004
Title of Invention:	METHODS OF FORMING INTEGRATED CIRCUITS DEVICES HAVING PAD CONTACT PLUGS IN THE CELL ARRAY AND PERIPHERAL CIRCUIT REGIONS OF THE INTEGRATED CIRCUIT SUBSTRATE
First Named Inventor/Applicant Name:	Se-Hoon Oh
Filer:	Elizabeth A. Stanek/Erin Dutton
Attorney Docket Number:	5649-1228

Filed as Large Entity

Utility Filing Fees

Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
Basic Filing:				
Pages:				
Claims:				
Miscellaneous-Filing:				
Petition:				
Patent-Appeals-and-Interference:				
Post-Allowance-and-Post-Issuance:				
Utility Appl issue fee	1501	1	1400	1400
Publ. Fee- early, voluntary, or normal	1504	1	300	300

Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
Extension-of-Time:				
Miscellaneous:				
Total in USD (\$)				1700